Din-Tek SEMICONDUCTOR

DTQ3D306

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N- and P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY				
	V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)[a]	Q_g (Typ.)
N-Channel	30	0.015 at V_{GS} = 10 V	18	12.5
		0.020 at V_{GS} = 4.5 V	14	
P-Channel	- 30	0.039 at V_{GS} = - 10 V	- 12	5
		0.060 at V_{GS} = - 4.5 V	- 8	

FEATURES

- DT-Trench Power MOSFET
- 100% R_g and UIS Tested

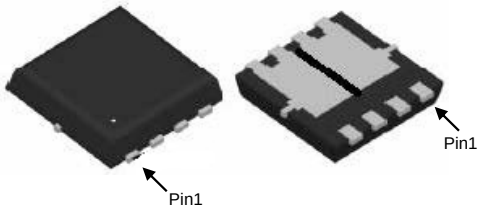
APPLICATIONS

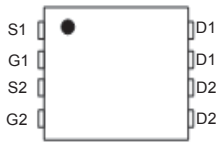
- Networking DC-DC Power System
- Load Switch

Pb-free

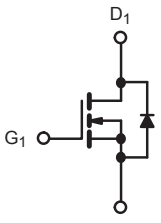
RoHS COMPLIANT

DFN 3.3x3.3

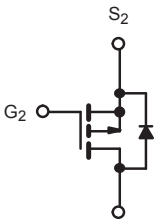




Top View



N-Channel MOSFET



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted					
Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		V_{DS}	30	- 30	V
Gate-Source Voltage		V_{GS}	± 20		
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	18	-12	A
	T_C = 70 °C		15	- 8	
	T_A = 25 °C		12 [b, c]	- 8.3 [b, c]	
	T_A = 70 °C		9.4 [b, c]	- 6.5 [b, c]	
Pulsed Drain Current		I_{DM}	72	-48	
Source-Drain Current Diode Current	T_C = 25 °C	I_S	15	- 10	
	T_A = 25 °C		8 [b, c]	- 5 [b, c]	
Pulsed Source-Drain Current		I_{SM}	72	-48	
Single Pulse Avalanche Current	L = 0 1 mH	I_{AS}	40	-27	
Single Pulse Avalanche Energy		E_{AS}	20	-12	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	12.5	6	W
	T_C = 70 °C		5	2.9	
	T_A = 25 °C		4.3 [b, c]	2.0 [b, c]	
	T_A = 70 °C		2.25 [b, c]	1.25 [b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS							
			N-Channel		P-Channel		
Parameter		Symbol	Typ.	Max.	Typ.	Max.	Unit
Maximum Junction-to-Ambient [b, d]	t ≤ 10 s	R_{thJA}	54	64	25	30	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	70	85	50	60	

Notes:
a. Based on T_C = 25 °C.
b. Surface Mounted on 1" x 1" FR4 board.
c. t = 10 s.
d. Maximum under Steady State conditions is 120 °C/W.

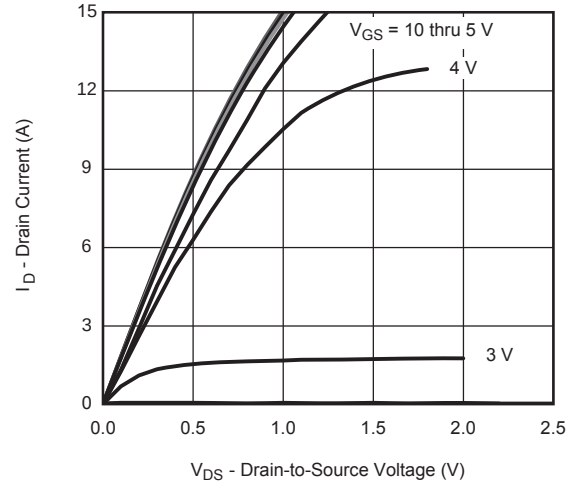
SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
Parameter	**Symbol**	**Test Conditions**		**Min.**	**Typ.[a]**	**Max.**	**Unit**
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	N-Ch	30			V
		V_{GS} = 0 V, I_D = - 250 µA	P-Ch	- 30			
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA	N-Ch		44		mV/°C
		I_D = - 250 µA	P-Ch		- 42		
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I_D = 250 µA	N-Ch		- 5.5		
		I_D = - 250 µA	P-Ch		4.6		
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	N-Ch	1		3	V
		V_{DS} = V_{GS}, I_D = - 250 µA	P-Ch	- 1		- 3	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V	N-Ch			100	nA
			P-Ch			- 100	
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 24 V, V_{GS} = 0 V	N-Ch			1	µA
		V_{DS} = - 24 V, V_{GS} = 0 V	P-Ch			- 1	
		V_{DS} = 24 V, V_{GS} = 0 V, T_J = 55 °C	N-Ch			10	
		V_{DS} = - 24 V, V_{GS} = 0 V, T_J = 55 °C	P-Ch			- 10	
On-State Drain Current[b]	$I_{D(on)}$	V_{DS} = 5 V, V_{GS} = 10 V	N-Ch	72			A
		V_{DS} = - 5 V, V_{GS} = - 10 V	P-Ch	- 48			
Drain-Source On-State Resistance[b]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 10 A	N-Ch		0.015	0.018	Ω
		V_{GS} = - 10 V, I_D = - 8 A	P-Ch		0.039	0.047	
		V_{GS} = 4.5 V, I_D = 8 A	N-Ch		0.020	0.025	
		V_{GS} = - 4.5 V, I_D = - 5 A	P-Ch		0.060	0.067	
Forward Transconductance[b]	g_{fs}	V_{DS} = 15 V, I_D = 10 A	N-Ch		25		S
		V_{DS} = - 15 V, I_D = - 8 A	P-Ch		12		
Dynamic[a]							
Input Capacitance	C_{iss}	N-Channel V_{DS} = 24 V, V_{GS} = 0 V, f = 1 MHz P-Channel V_{DS} = - 24 V, V_{GS} = 0 V, f = 1 MHz	N-Ch		650		pF
			P-Ch		570		
Output Capacitance	C_{oss}		N-Ch		190		
			P-Ch		80		
Reverse Transfer Capacitance	C_{rss}		N-Ch		95		
			P-Ch		45		
Total Gate Charge	Q_g	V_{DS} = 24 V, V_{GS} = 10 V, I_D = 10 A	N-Ch		12.5	22	nC
		V_{DS} = - 24 V, V_{GS} = - 10 V, I_D = - 8 A	P-Ch		5	18	
		N-Channel V_{DS} = 24 V, V_{GS} = 4.5 V I_D = 8 A P-Channel V_{DS} = - 24 V, V_{GS} = - 4.5 V, I_D = - 5 A	N-Ch		5.3	9	
			P-Ch		1.8	3	
Gate-Source Charge	Q_{gs}		N-Ch		1.4		
			P-Ch		0.55		
Gate-Drain Charge	Q_{gd}		N-Ch		1.9		
			P-Ch		1.1		
Gate Resistance	R_g	f = 1 MHz	N-Ch	0.5	2.0	4.5	Ω
			P-Ch	1.0	3.5	11	

SPECIFICATIONS T_J = 25 °C, unless otherwise noted							
Parameter	**Symbol**	**Test Conditions**		**Min.**	**Typ.[a]**	**Max.**	**Unit**
Dynamic[a]							
Turn-On Delay Time	$t_{d(on)}$	N-Channel V_{DD} = 24 V, R_L = 4 Ω, $I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω	N-Ch		7	14	ns
			P-Ch		8	17	
Rise Time	t_r		N-Ch		10	25	
			P-Ch		13	27	
Turn-Off Delay Time	$t_{d(off)}$	P-Channel V_{DD} = - 24 V, R_L = 4 Ω, $I_D \cong$ - 8 A, V_{GEN} = - 10 V, R_g = 1 Ω	N-Ch		15	32	
			P-Ch		33	65	
Fall Time	t_f		N-Ch		9	22	
			P-Ch		9	23	
Turn-On Delay Time	$t_{d(on)}$	N-Channel V_{DD} = 24 V, R_L = 4 Ω, $I_D \cong$ 8 A, V_{GEN} = 4.5 V, R_g = 1 Ω	N-Ch		16	30	
			P-Ch		47	80	
Rise Time	t_r		N-Ch		19	30	
			P-Ch		33	50	
Turn-Off Delay Time	$t_{d(off)}$	P-Channel V_{DD} = - 24 V, R_L = 4 Ω, $I_D \cong$ - 5 A, V_{GEN} = - 4.5 V, R_g = 1 Ω	N-Ch		16	30	
			P-Ch		28	60	
Fall Time	t_f		N-Ch		10	20	
			P-Ch		13	25	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C	N-Ch			15	A
			P-Ch			-10	
Pulse Diode Forward Current[a]	I_{SM}		N-Ch			72	
			P-Ch			-48	
Body Diode Voltage	V_{SD}	I_S = 1.6 A	N-Ch		0.78	1.2	V
		I_S = - 1.6 A	P-Ch		- 0.76	- 1.2	
Body Diode Reverse Recovery Time	t_{rr}	N-Channel I_F = 2 A, dI/dt = 100 A/µs, T_J = 25 °C	N-Ch		7	34	ns
			P-Ch		5	55	
Body Diode Reverse Recovery Charge	Q_{rr}		N-Ch		4	25	nC
			P-Ch		1.5	35	
Reverse Recovery Fall Time	t_a	P-Channel I_F = - 2 A, dI/dt = - 100 A/µs, T_J = 25 °C	N-Ch		17		ns
			P-Ch		19		
Reverse Recovery Rise Time	t_b		N-Ch		6		
			P-Ch		15		

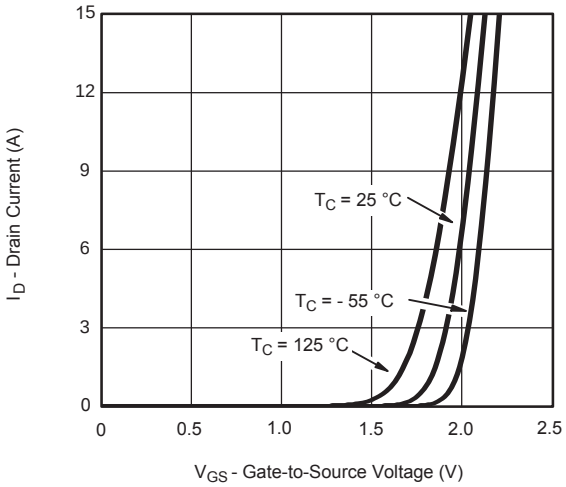
Notes:
a. Guaranteed by design, not subject to production testing.
b. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

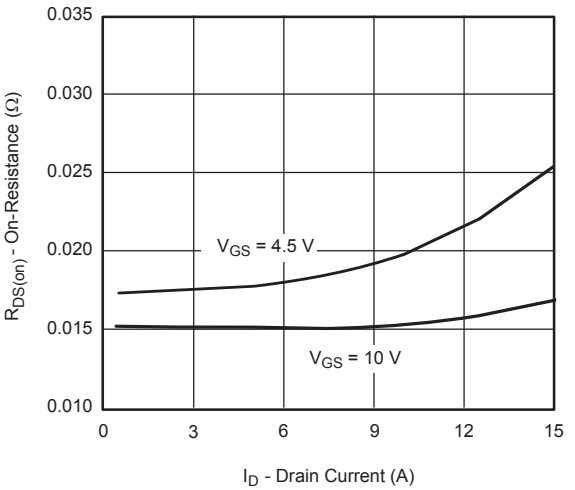
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



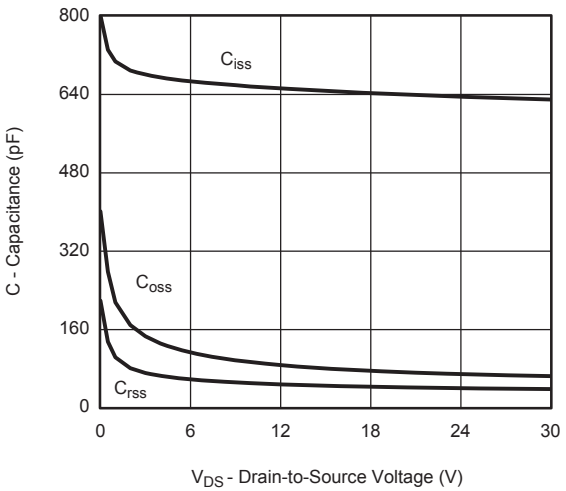
Output Characteristics



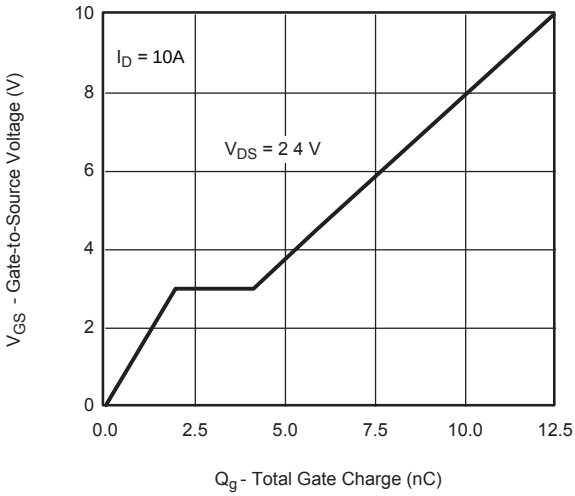
Transfer Characteristics



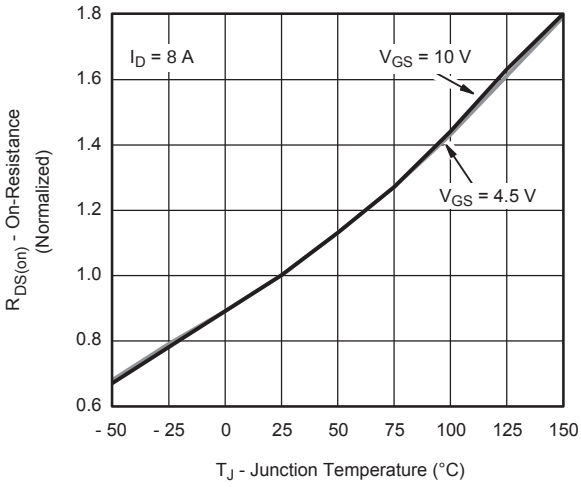
On-Resistance vs. Drain Current



Capacitance

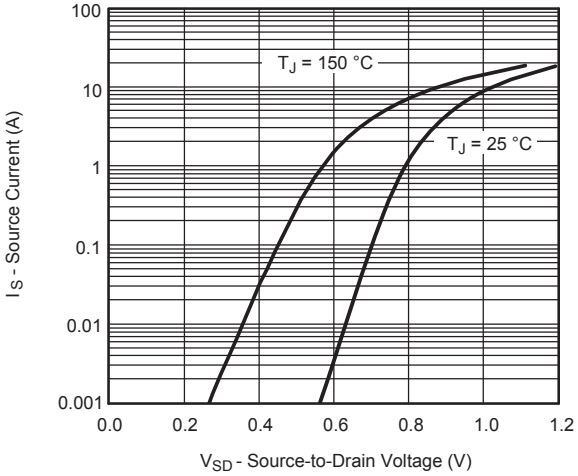


Gate Charge

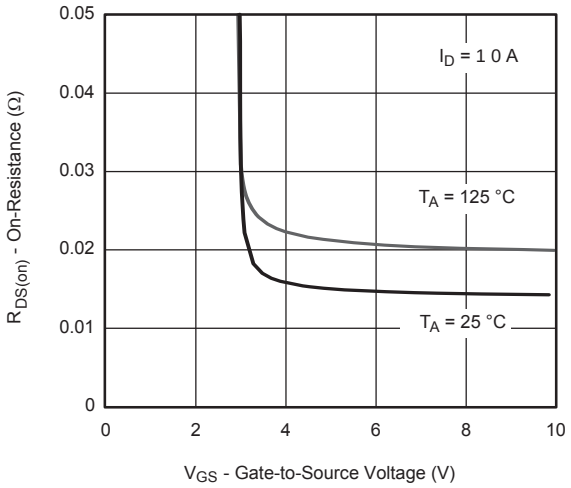


On-Resistance vs. Junction Temperature

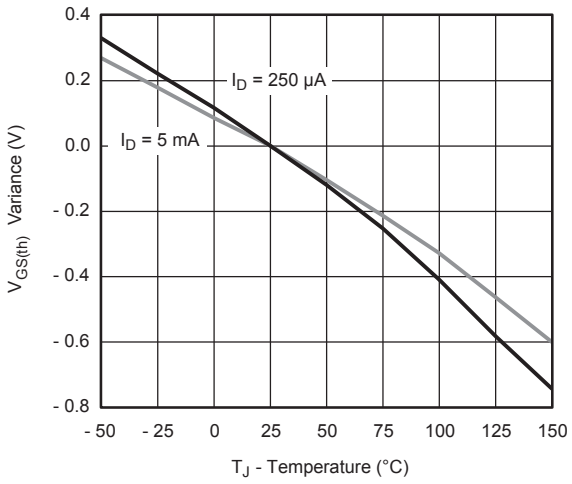
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



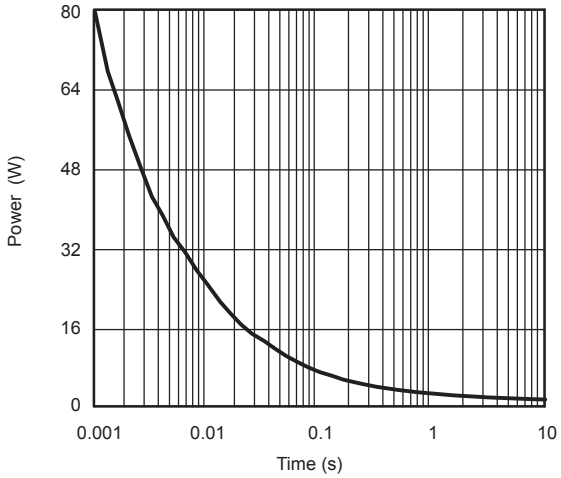
Source-Drain Diode Forward Voltage



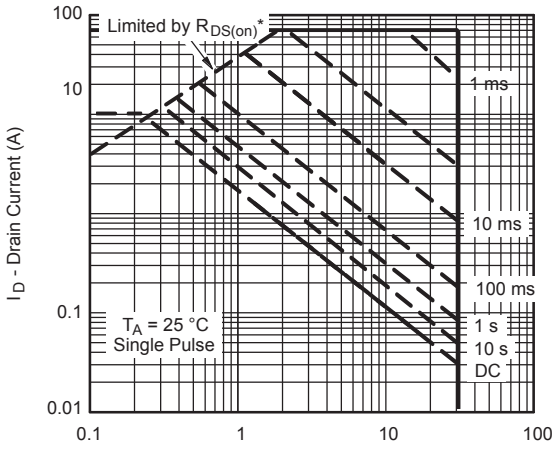
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



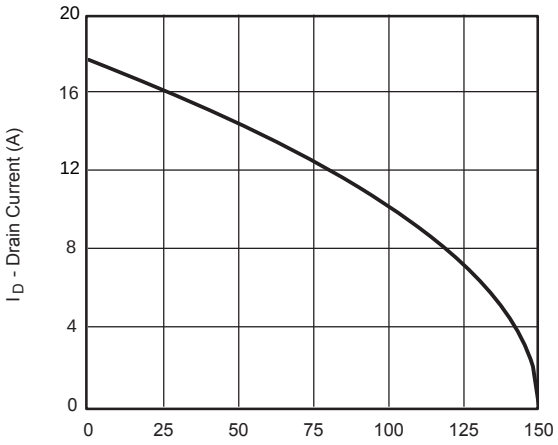
Single Pulse Power, Junction-to-Ambient



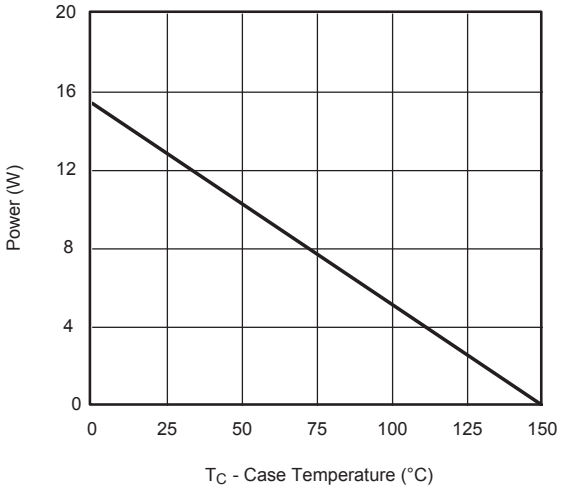
* V_{GS} > minimum V_{GS} at which $r_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

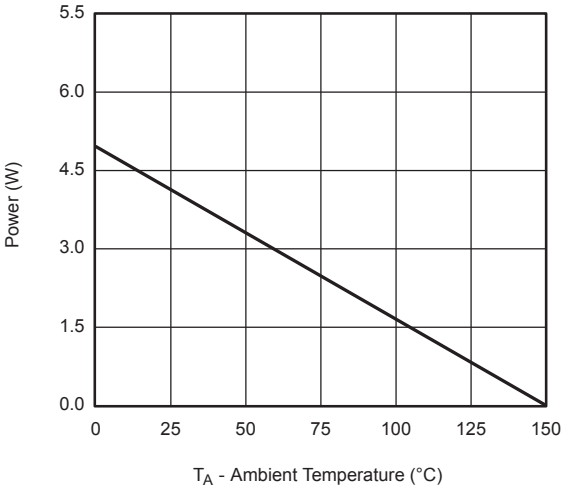
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



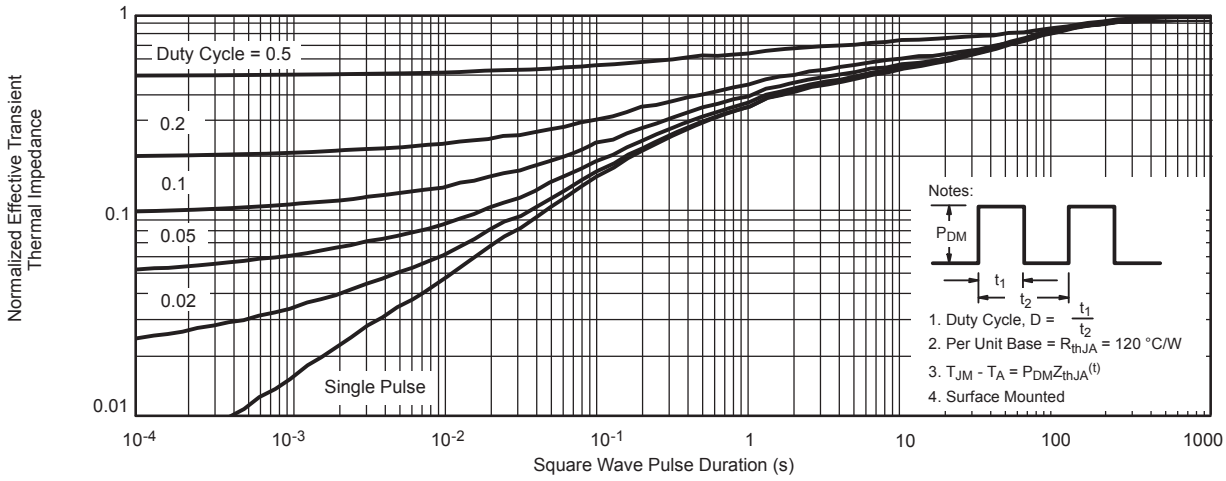
Power Derating, Junction-to-Foot



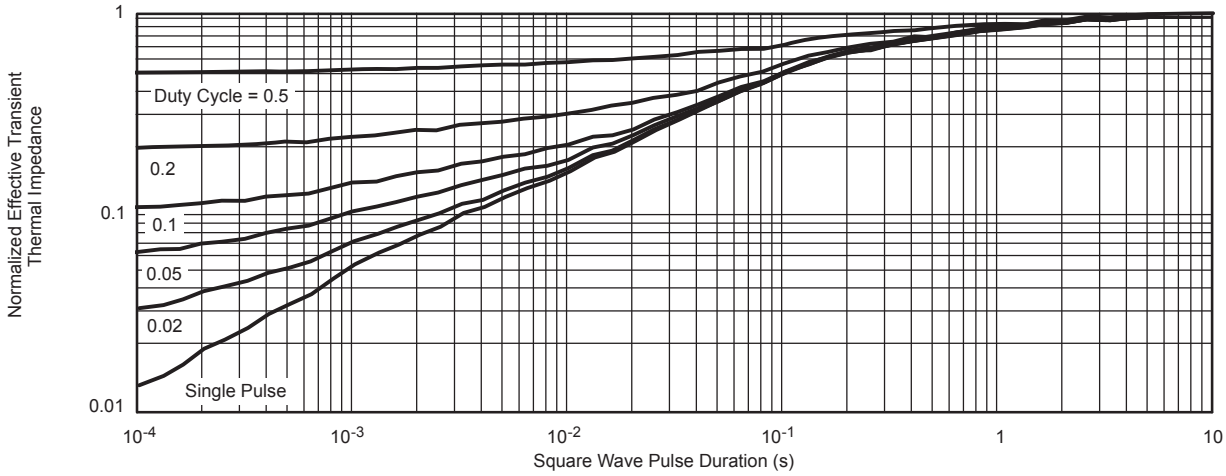
Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

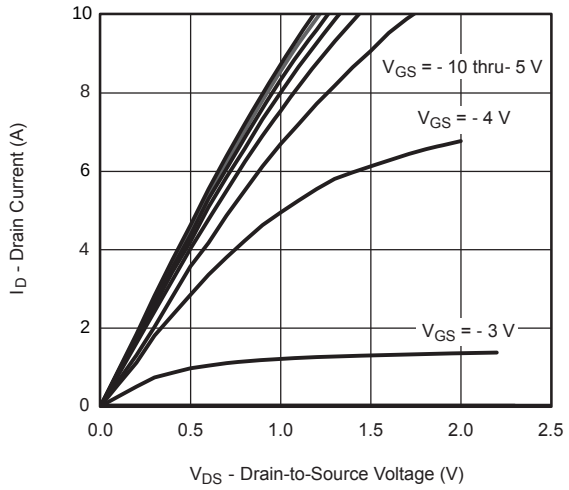


Normalized Thermal Transient Impedance, Junction-to-Ambient

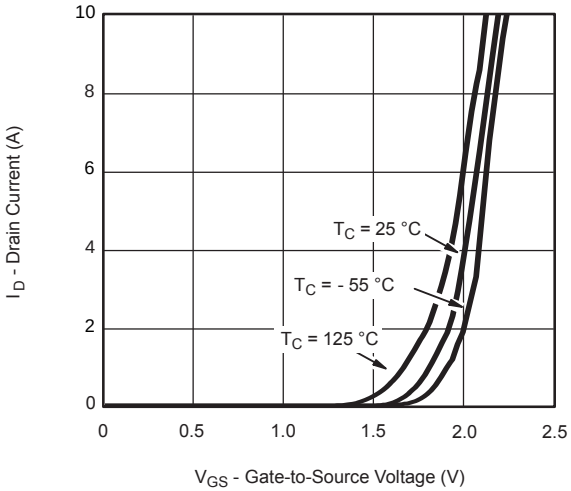


Normalized Thermal Transient Impedance, Junction-to-Foot

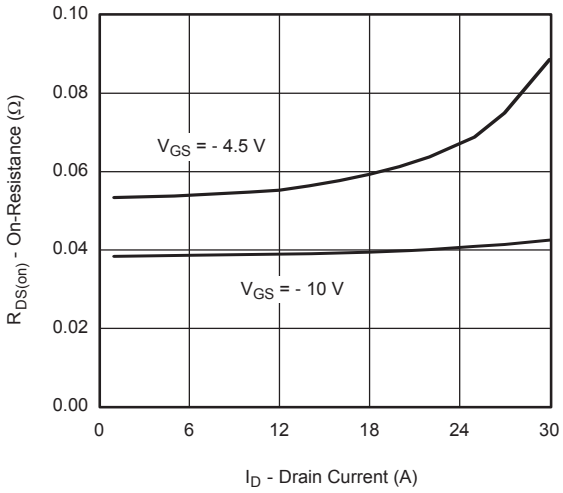
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



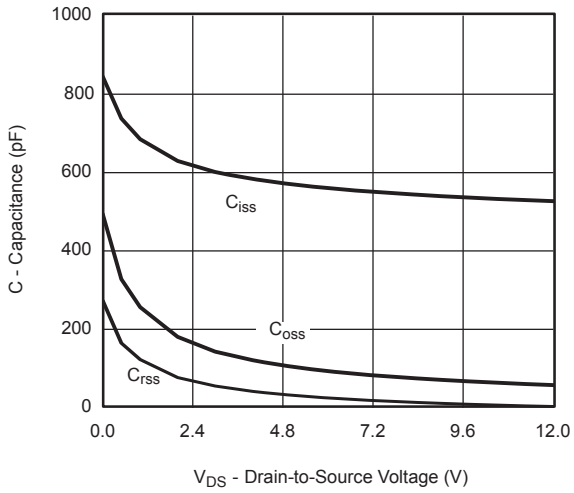
Output Characteristics



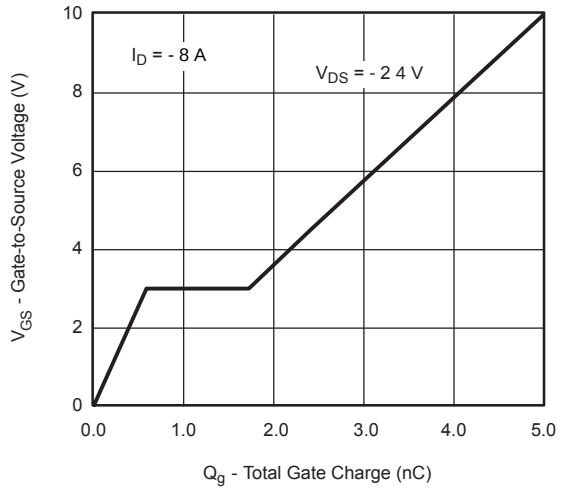
Transfer Characteristics



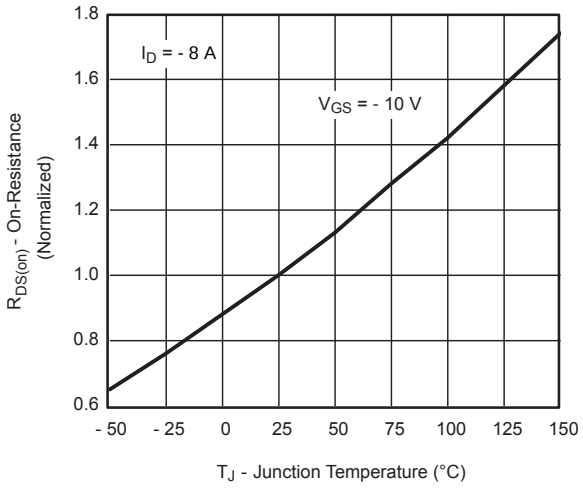
On-Resistance vs. Drain Current



Capacitance

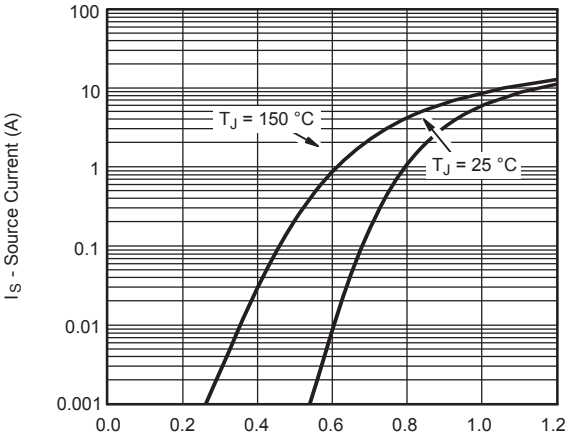


Gate Charge

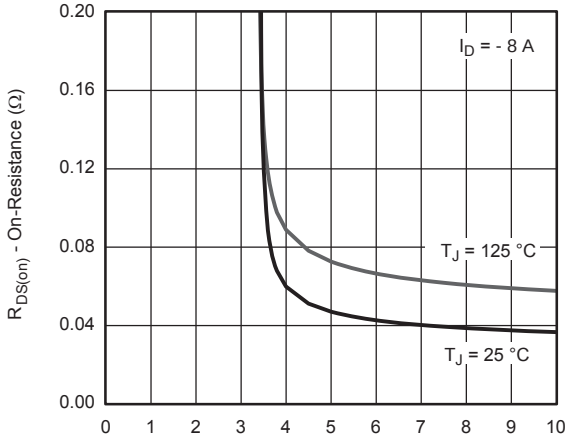


On-Resistance vs. Junction Temperature

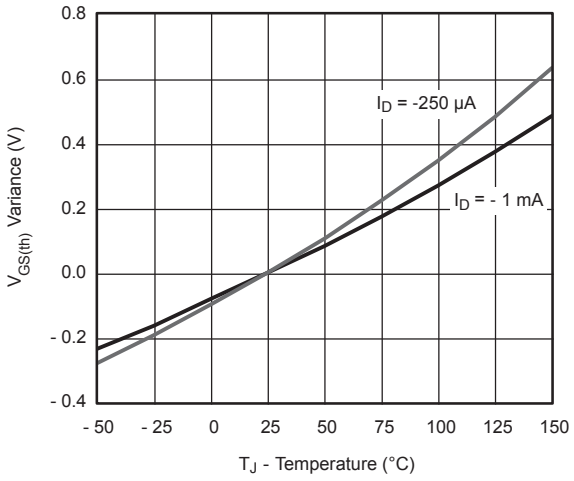
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



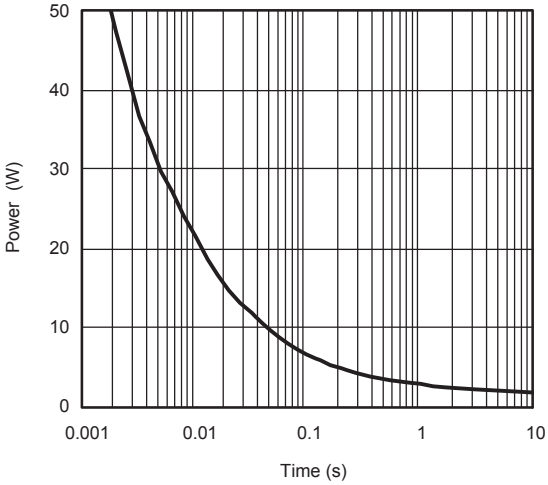
Source-Drain Diode Forward Voltage



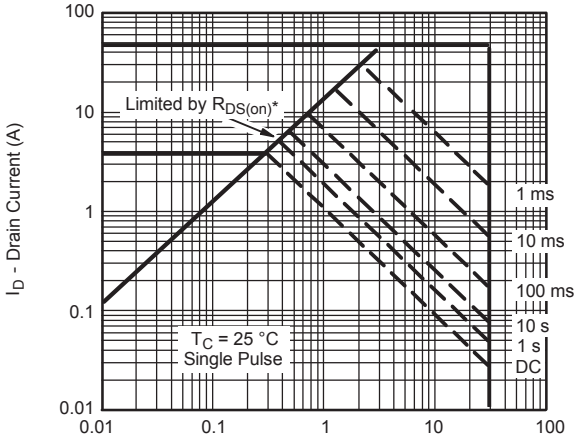
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



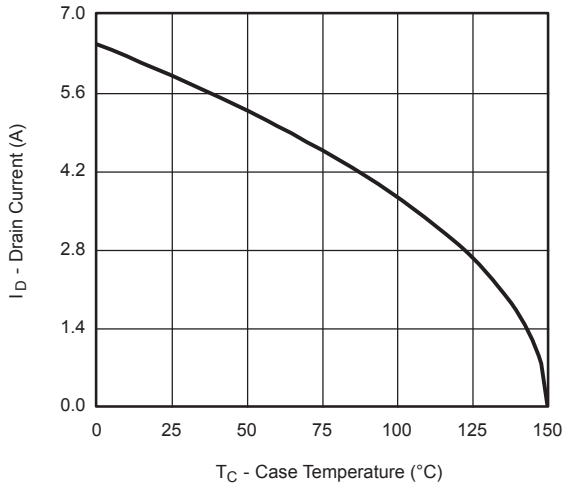
Single Pulse Power, Junction-to-Ambient



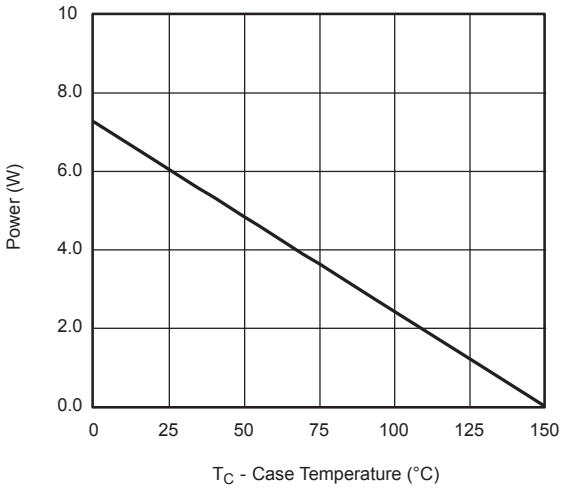
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

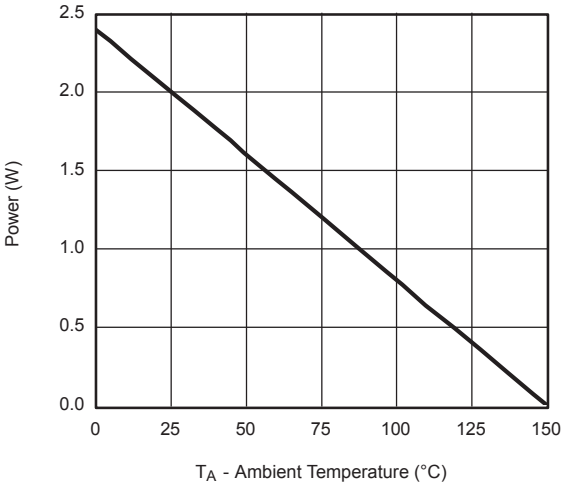
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



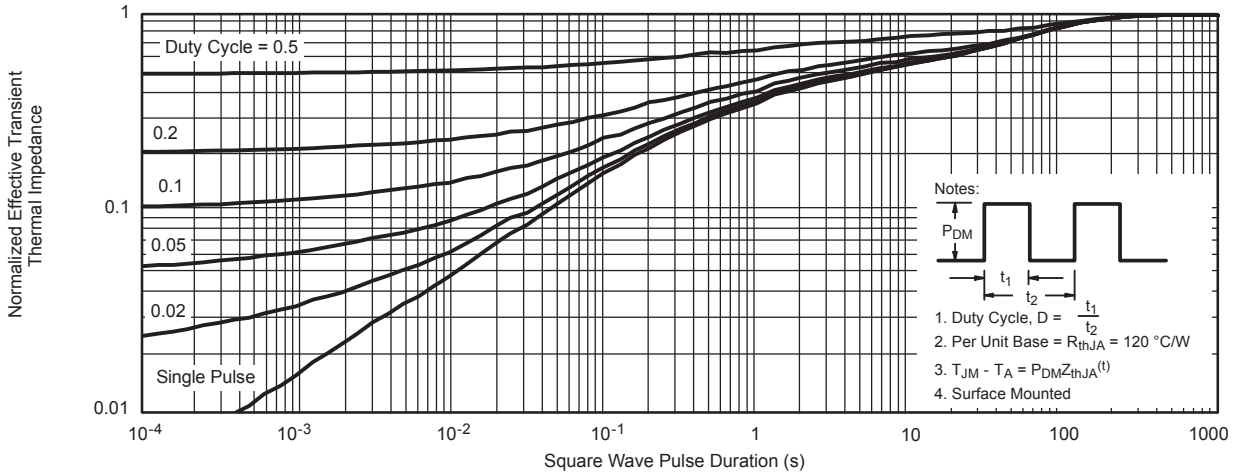
Power Derating, Junction-to-Foot



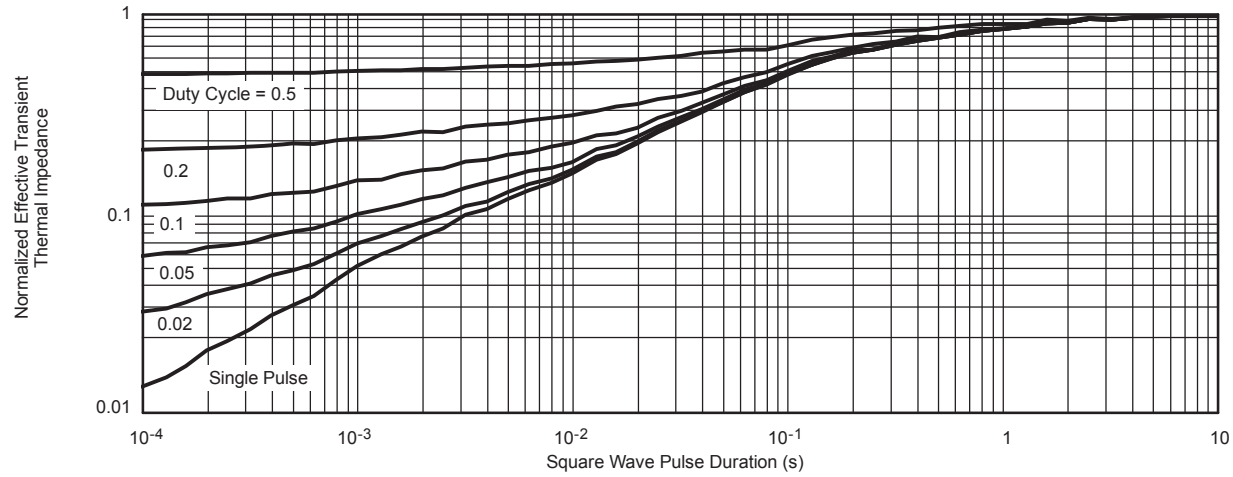
Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

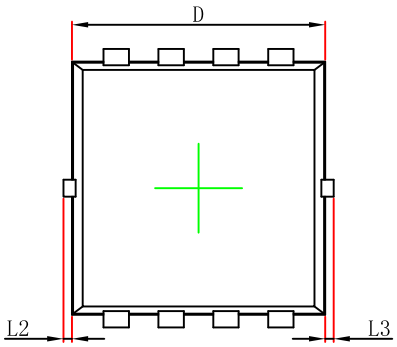


Normalized Thermal Transient Impedance, Junction-to-Ambient

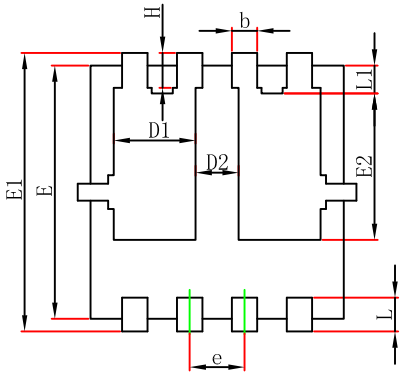


Normalized Thermal Transient Impedance, Junction-to-Foot

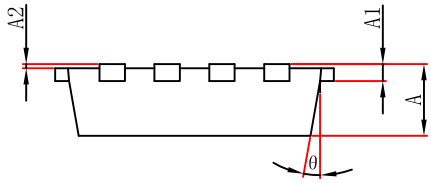
PDFNWB(3.3×3.3)-8L-B(P0.65T0.80) PACKAGE OUTLINE DIMENSIONS



Top View



Bottom View



Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°

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